



Material Content Data Sheet



Sales Product Name				IPD600N25N3 G		Issued		1. August 2018	
MA#				MA000812210					
Package				PG-TO252-3-11		Weight*		368.72 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.322	1.71	1.71	17145	17145	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175		
	non noble metal	iron	7439-89-6	0.215	0.06		584		
	non noble metal	copper	7440-50-8	215.017	58.32	58.40	583141	583900	
	non noble metal	aluminium	7429-90-5	4.494	1.22	1.22	12189	12189	
wire	non noble metal	aluminium	7429-90-5	4.494	1.22	1.22	12189	12189	
encapsulation	organic material	carbon black	1333-86-4	1.146	0.31		3109		
	inorganic material	antimonytrioxide	1309-64-4	2.292	0.62		6217		
	plastics	brominated resin	-	2.292	0.62		6217		
	plastics	epoxy resin	-	22.925	6.22		62174		
	inorganic material	silicondioxide	60676-86-0	85.969	23.32	31.09	233153	310870	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10143	10143	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	246	247	
solder	non noble metal	tin	7440-31-5	0.099	0.03		269		
	noble metal	silver	7440-22-4	0.124	0.03		336		
	non noble metal	lead	7439-92-1	4.728	1.28	1.34	12823	13428	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.20	5.21	52010	52078	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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